

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Applicant: Kie Y. Ahn et al.

Title: MULTILEVEL COPPER INTERCONNECTS WITH LOW-K DIELECTRICS AND AIR GAPS

Docket No.: 303.686US3

Serial No.: 10/786,354

Filed: February 25, 2004

Due Date: September 25, 2004

Examiner: Andy Huynh

Group Art Unit: 2818

Mail Stop Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

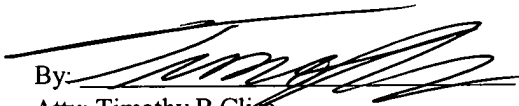
We are transmitting herewith the following attached items (as indicated with an "X"):

- ☒ A return postcard.
- ☒ A Response to Restriction Requirement (1 Page).
- ☒ A Communication Concerning Related Applications (1 pg.).
- ☒ A Supplemental Information Disclosure Statement (2 pgs.), Form 1449 (1 pg.), and copies of 5 cited documents.

Please consider this a **PETITION FOR EXTENSION OF TIME** for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

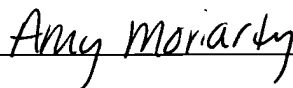
SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

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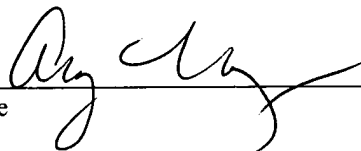
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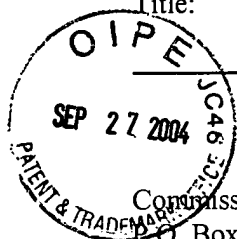
(GENERAL)

S/N 10/786,354

PATENT

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Applicant: Kie Y. Ahn et al. Examiner: Andy Huynh
Serial No.: 10/786,354 Group Art Unit: 2818
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Title: MULTILEVEL COPPER INTERCONNECTS WITH LOW-K DIELECTRICS AND
AIR GAPS



COMMUNICATION CONCERNING RELATED APPLICATION(S)

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Applicants would like to bring to the Examiner's attention the following related application(s) in the above-identified patent application:

<u>Serial/Patent No.</u>	<u>Filing Date</u>	<u>Attorney Docket</u>	<u>Title</u>
09/854540	May 14, 2001	1303.013US1	COPPER DUAL DAMASCENE INTERCONNECT TECHNOLOGY
09/583514 6423629	May 31, 2000	303.686US1	MULTILEVEL COPPER INTERCONNECTS WITH LOW-K DIELECTRICS AND AIR GAPS
10/093244	March 6, 2002	303.686US2	MULTILEVEL COPPER INTERCONNECTS WITH LOW-K DIELECTRICS AND AIR GAPS
10/842243	May 10, 2004	1303.013US2	COPPER DUAL DAMASCENE INTERCONNECT TECHNOLOGY

Respectfully submitted,
KIE Y. AHN ET AL.
By Applicants' Representatives,
SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
P.O. Box 2938
Minneapolis, MN 55402
(612) 349-9587

Date

24 Sept '04

By

Timothy B. Chase
Reg. No. 40,957

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Name

Amy Moriarty

Signature

Amy Moriarty